



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



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The marking on this product doesn't contain environmental hazardous material and must follow one or more specifications per Material Specification SS-00259 for Sony GP compliant or per directive 2011/65/EC for RoHS compliant or per IEC 61249-2-21 for Halogen Free compliant.

PART NUMBER:
GSB3 112 X X HR

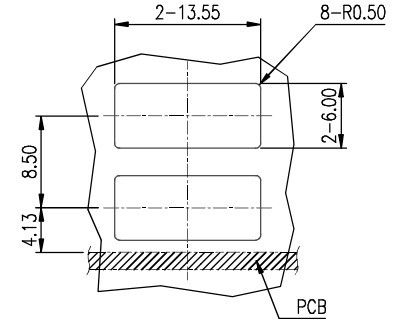
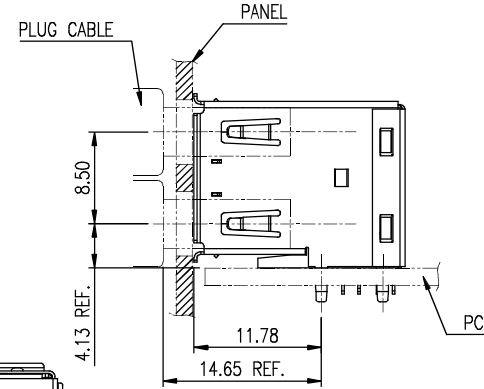
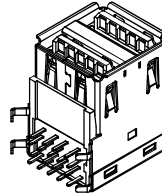
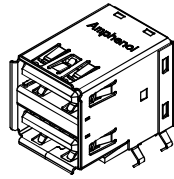
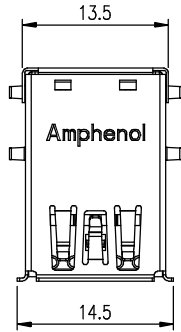
ORIGINAL

REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	BY
A		RELEASE TO PRODUCTION	07/02/2010	Sondra Sang
B	NE-10119	MODIFIED THE FRONT SHELL PLATING	07/28/2010	Sondra Sang
C	NE-10123	MODIFIED PNS	08/06/2010	Sondra Sang
D	NE-10161	MODIFIED MATERIAL	10/06/2010	Sondra Sang
E	NE-11083	ADDED PANEL CUTOUT	06/23/2011	Sondra Sang
F	NE-14014	MODIFIED PNS ADDED OPTIONS	01/22/2014	Sondra Sang

CONTACT FINISH
3: 30μ" GOLD
4: 2μ" GOLD+
30μ" Ni-Pd

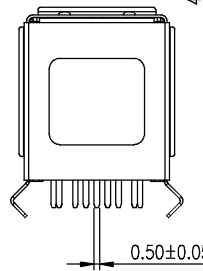
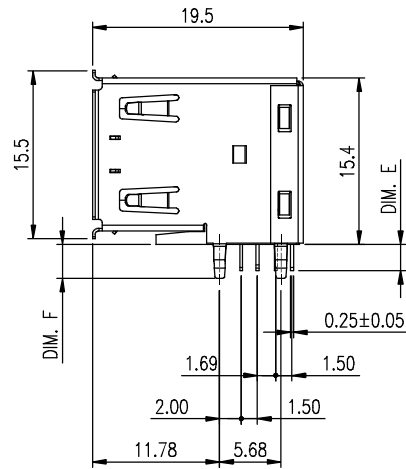
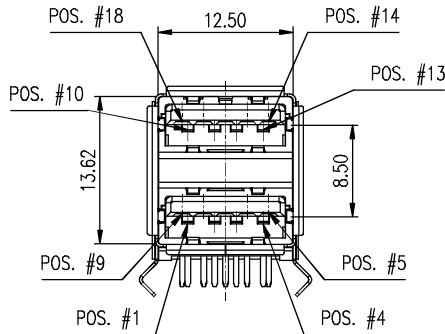
SOLDER TAIL LENGTH
BLANK: Standard (2.4mm)
1: 3.00mm

INSULATOR AND COLOR
1: LCP, Blue
3: LCP, Black
4: Nylon, Blue
6: Nylon, Black



RECOMMEND MOUNTING CONFIGURATION

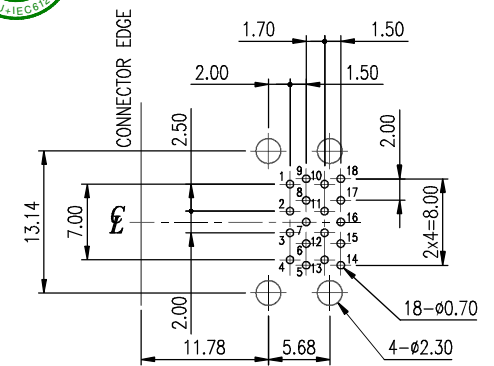
RECOMMEND PANEL CUTOUT



PART NO	DIM. E	DIM. F
GSB3112XXHR	2.4	3.0
GSB3112XX1HR	3.0	3.5

PIN #	PIN #	SIGNAL NAME
1	10	VBUS
2	11	D-
3	12	D+
4	13	GND
5	14	SSRX-
6	15	SSRX+
7	16	GND_DRAIN
8	17	SSTX-
9	18	SSTX+
SHELL		SHIELD

PIN ASSIGNMENT



RECOMMENDED PCB LAYOUT- TOP VIEW
(GENERAL TOLERANCE: ±0.05)



- NOTES:
- HOUSING: HIGH TEMPERATURE THERMOPLASTIC, UL 94V-0 OR 94H-B, COLOR- BLUE (PANTONE 300C) OR BLACK
 - BOTTOM COVER: HIGH TEMPERATURE THERMOPLASTIC, UL 94V-0, COLOR- BLUE (PANTONE 300C) OR BLACK
 - CONTACT: COPPER ALLOY, 0.25mm THICKNESS, 30μ" MIN. GOLD or 2μ" MIN. GOLD +30μ" MIN. Ni-Pd PLATED ON CONTACT AREA, 120μ" MIN. MATTE TIN PLATED ON SOLDERING TAIL, 80μ" MIN. NICKEL UNDER-PLATED OVERALL
 - FRONT SHELL: STAINLESS STEEL, 0.25mm THICKNESS, 30μ" MIN. NICKEL PLATED OVER ALL
 - MIDDLE SHELL: STAINLESS STEEL, 0.25mm THICKNESS,
 - REAR SHELL: STAINLESS STEEL, 0.2mm THICKNESS,
 - THIS PRODUCT DOESN'T CONTAIN ENVIRONMENTAL HAZARDOUS MATERIALS PER DIRECTIVE 2011/65/EC FOR RoHS AND PER IEC 61249-2-21 FOR HALOGEN FREE COMPLIANT.

TOLERANCE	APPROVALS	DATE	TITLE
X. ±0.30	DRAWN Sondra Sang	1/22/2014	USB 3.0 CONNECTOR STANDARD A, STACKED, R/A DIP TYPE
X.X ±0.20			
X.XX ±0.20	CHECKED Chenny Yeh	1/22/2014	
X.XXX ±0.10	APPROVED Hank Hsu	1/22/2014	
ANGULAR ±1°	DWG TYPE CUST DWG	PROJECT CODE 1510	UNIT mm SCALE NA
UNLESS OTHERWISE SPECIFIED			SIZE A3 SHEET 1 OF 1

Amphenol®
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PART No. GSB3 112 XX XHR
DVG No. GSB311231HR
REV. F